



CALL FOR PAPERS

The 2023 IEEE International Symposium on Power Line Communications and its Applications (ISPLC) will be the 26th symposium dedicated to scientific and technical advances in the field of communications over power lines. The event is sponsored by IEEE Communications Society (IEEE ComSoc). The conference will be held in Manchester, United Kingdom, from 21st to 23rd March, 2023. One of the main features of ISPLC is strong industry participation; it brings together researchers, practitioners and users of PLC technology. The conference will further include a series of keynote and experts' panel talks, as well as an Industry Exhibit centred on PLC for Smart Grids. In this edition, contributions can be submitted to any of the following four types of sessions:

Type of submission	Target	Acceptance criteria	Publication
Regular Technical	Unpublished works	Peer review	Proceedings & IEEE Xplore®
Dissemination	Works already published in journal papers	TPC co-chairs	Only to attendees and subject to authors' authorization
Industrial & standardization	Ongoing or recent industrial developments, specifications, standards and prototypes	TPC	Only to attendees
Recent results	Ongoing research and preliminary results	TPC co-chairs	Only to attendees

Check the [website](#) for full details of procedures and requirements for the different submissions. Acceptance of submissions will be based on quality, relevance, and originality, with awards for the best submissions. Accepted papers will be published in the IEEE ISPLC 2023 Conference Proceedings and in IEEE Xplore®. Submissions are invited in, but not limited to, the following areas

- Noise effects over PLC, Channel characterization, modelling, emulation, and experimental systems
- MIMO, Modulation, coding and signal processing for PLC
- Non-orthogonal multiple access for PLC
- Access, in-home and in-vehicle power line networks
- System architectures integrating PLC
- Broadband and multimedia applications
- PLC for Smart Metering, Distribution Automation,
- PLC integration with electric grid assets
- Experience from large scale PLC roll-outs
- Performance measurements and comparability of field trials
- Cooperative technologies with PLC/hybrid systems
- PLC standardization and regulation
- Emerging PLC-related technologies
- Network and service management
- Electromagnetic compatibility and interference
- Coexistence and interoperability
- Measurement concepts, protocols and tools for PLC
- Operation and management for PLC networks
- Green communications and energy saving concepts for PLC modems
- Cross-layer optimization and service integration
- Cybersecurity in PLC

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Important Dates:

Paper registration due: 23rd October 2022

Full Paper Due: 1st November 2022

Notification of Acceptance: 6th January 2023

Camera-ready papers Due: 9th February 2023

For more information about this conference, please visit <http://sites.ieee.org/isplc-2023/>

PLEASE NOTE: To be published in the IEEE ISPLC 2023 Conference Proceedings and to be eligible for publication in IEEE Xplore®, an author of an accepted paper is required to register for the conference at the full (member or non-member) rate and the paper must be presented by an author of that paper at the conference unless the TPC Chair grants permission for a substitute presenter arranged in advance of the event and who is qualified both to present and answer questions. Non-refundable registration fees must be paid prior to uploading the final IEEE formatted, publication-ready version of the paper. For authors with multiple accepted papers, one full registration is valid for up to 3 papers. Accepted and presented papers will be published in the IEEE ISPLC 2023 Conference Proceedings and submitted to IEEE Xplore® as well as other Abstracting and Indexing (A&I) databases.